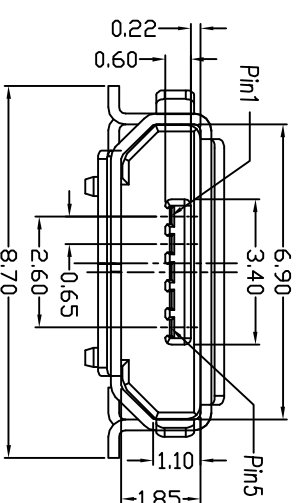
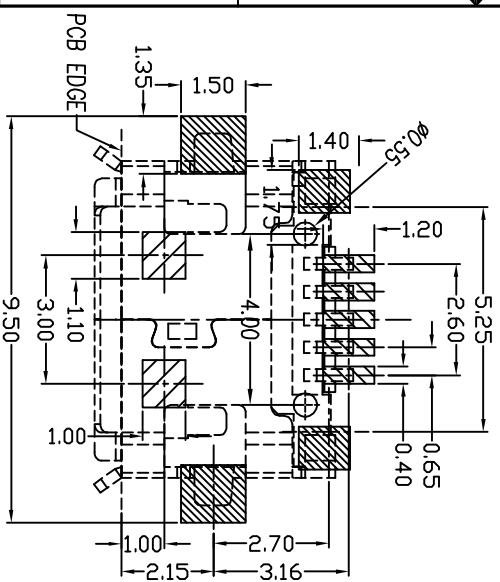
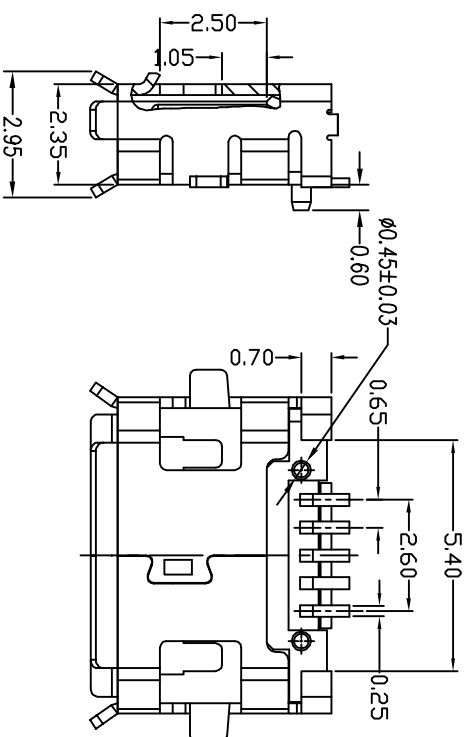
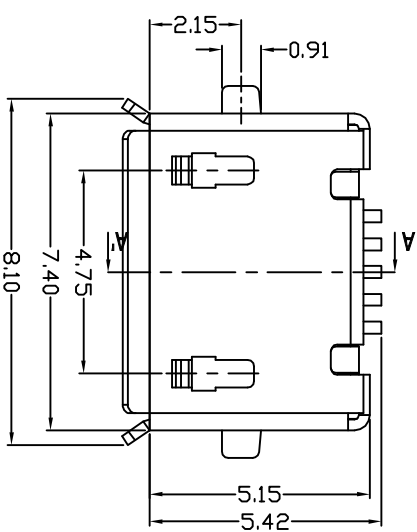
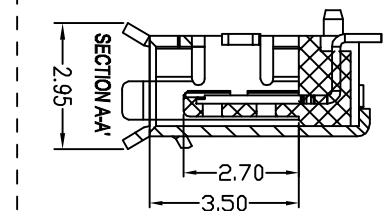
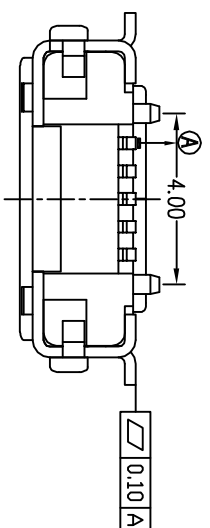


REV.	EQN NO	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD



Notes:

1. Materials:
  - 1.1 Housing: High temperature thermoplastic with g.f, UL94 v-0.
  - 1.2 Contact: copper alloy t=0.20mm.
  - 1.3 Shell: copper alloy t=0.25mm.
2. Specifications:
  - 2.1. Current rating: 1 A Max.
  - 2.2. Dielectric withstanding: voltage: 100 V(ac) for 1 min.
  - 2.3. Contact resistance: 50 mW Max.
  - 2.4. Insulation resistance: 100 MW Min.
  - 2.5. Total mating force: 3.57 Kgf Max.
  - 2.6. Total unmating force: 1.0 Kgf Min. 0.81~2.05 Kgf Min. after 10000 insertion/extraction cycles
  - 2.7. Temperature range: -30°C~+80°C

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Micro usb 5P/F B Type SMT 有导线  
(外壳厚度为 8.7)

No.	Nome	Q'ty	Finish
3	Shell	1	N/A
2	Contact	5	N/A
1	Housing	1	N/A

PART NO: I-MD05SMXXX-01	MATERIAL: SEE NOTE
MODEL NO:	FINSH: SEE NOTE
UNIT: mm	SIZE: A4
TOLERANCE UNSPECIFIED	
.x	±0.38
.xx	±0.25
.xxx	±0.13
ANG.	±2°

DR:	COLOR: SEE NOTE	TITLE:
CHK:	DWG NO: SHK-20039	SCALE: 1:1
APP:	SHEET: 1/1	REV: A